

AMENDMENTS TO THE SPECIFICATION:

Please amend the paragraph beginning at line 13 of page 16 as follows:

The electrodeposited copper foil with low roughness surface (electrodeposited copper foil, without treatment) thus obtained was measured for expansive force (MPa) and percent elongation (%) at room temperature (about 25°C) and at 180°C in accordance with IPC-TM-650 using Type 2001 tension tester available from INTESCO Co., Ltd., and measured for surface roughness (Rz) of roughness surface in accordance with JIS B 0601 using SURFCORDER SE 1700 α available from Kosaka Laboratory Ltd. As an index for indicating degree of uneven surge on the roughness surface of the electrodeposited copper foil with low roughness surface, mirror gloss of the roughness surface was measured in two directions along width and length (flow) of the electrodeposited copper foil with low roughness surface in accordance with JIS Z 8741, using a gloss meter available from Minolta Co., Ltd. (product name: MULTIGLOSS TYPE 268) and by Gs (85°). Measurement results are shown in Table [[1]] 2.